

FOR ADDITIONAL INFORMATION CONTACT

Phone: (518) 452-2880

E-Mail: info@yincae.com



YINCAE Advanced Materials, LLC

19 Walker Way, Albany, NY, 12205

FOR IMMEDIATE RELEASE

Press Release

BP 256 Ball Attach Adhesive

(Albany, NY) 06/06/2017 — BP 256 is YINCAE's new ball attach adhesive product. BP 256 has been designed to enhance solder joint reliability and eliminate cleaning processes for LEAD-FREE ball bumping procedures on CSP, BGA, Flip chip, and PoP devices. It is compatible with current SMT assembly processes.

BP 256 is generally applied via printing or pin transfer methods and can replace traditional solder paste, flux, and underfill. During reflow, BP 256 encapsulates individual solder joints improving both reliability and drop test performance. This product also has the benefit of being 100% reworkable. BP 256 is commercially available and is currently being used for ball bumping applications.

For more information on YINCAE's BP256, or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

* * * * *

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of thermal interface materials, underfill solutions, die attach adhesives, electronic materials, & high-performance coatings used in microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

###

The YINCAE brand name and logo are trademarks of YINCAE Advanced Materials, LLC.